

External_Type	Material_Group	Substances	CAS_Number	Mass	Mass_Percentage_in_Leaf	Massmg
Solder Wire	Pure metal	Tin (Sn)	7440-31-5	0.00563	5.0	0.29215
	Pure metal	Silver (Ag)	7440-22-4	0.00169	1.5	0.08764
	Pure metal	Lead (Pb)	7439-92-1	0.10532	93.5	5.46311
<b>Subtotal</b>				<b>0.11264</b>	<b>100</b>	<b>5.8429</b>
Wire	Pure metal	Aluminium (Al)	7429-90-5	0.13495	100.0	7
<b>Subtotal</b>				<b>0.13495</b>	<b>100</b>	<b>7</b>
Die	Doped Silicon	Silicon (Si)	7440-21-3	0.15809	100.0	8.2
<b>Subtotal</b>				<b>0.15809</b>	<b>100</b>	<b>8.2</b>
Lead Frame	Copper alloy	Phosphorous (P)	7723-14-0	0.01914	0.03	0.993
	Copper alloy	Iron (Fe)	7439-89-6	0.06381	0.1	3.31
	Copper alloy	Copper (Cu)	7440-50-8	63.7299	99.87	3305.697
<b>Subtotal</b>				<b>63.81285</b>	<b>100</b>	<b>3310</b>
Post-plating	Pure metal	Tin (Sn)	7440-31-5	0.67476	100.0	35
<b>Subtotal</b>				<b>0.67476</b>	<b>100</b>	<b>35</b>
Mould Compound	Polymer	Phenol Formaldehyde resin (generic)	9003-35-4	1.5798	4.5	81.945
	Polymer	Epichlorohydrin/Diethyleneglycol Epoxy resin (generic)	25928-94-3	3.51067	10.0	182.1
	Filler	Silica fused	60676-86-0	26.33003	75.0	1365.75
	Metal hydroxide	Metal hydroxide		3.51067	10.0	182.1
	Carbon Black	Carbon black	1333-86-4	0.17553	0.5	9.105
<b>Subtotal</b>				<b>35.1067</b>	<b>100</b>	<b>1821</b>
<b>Total</b>				<b>99.99999</b>	<b>100</b>	<b>5187.0429</b>

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